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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit of Parent: 2827
Examiner of Parent: David A. ZARNEKE
Confirmation No.: 1362

In Re PATENT APPLICATION OF:

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|-------------|-----------------------------------|---|------------------|
| Applicant: | Takaaki SASAKI |) | |
| | |) | |
| Serial No.: | 10/770,472 |) | |
| | |) | |
| Filed: | February 4, 2004 |) | |
| | |) | AMENDMENT |
| For: | SEMICONDUCTOR PACKAGE FOR THREE- |) | |
| | DIMENSIONAL MOUNTING, FABRICATION |) | |
| | METHOD THEREOF, AND |) | |
| | SEMICONDUCTOR DEVICE |) | |
| | |) | |
| Docket No.: | TAI 131-D1 |) | _____ |

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This paper is in response to the Official Action mailed on June 9, 2005. No fee is due. However, please charge our Deposit Account No. 18-0002 if any fees are needed to enter this paper, and please advise us accordingly. It is noted that no petition is required because of the authorization to charge, but please consider this paper a petition for extension of time if needed.

Support for Claim Amendments: The specification at page 14, last paragraph, explains that the registration marks L, shown in Fig. 6 in the corners of the substrate 4, are used as a reference for drilling the holes H with a laser beam. Fig. 6 shows that the registration marks L are exposed, being outside of the borders of the resin layer 6, and remain visible when the central area of the substrate 4 is covered with resin. Fig. 6 also shows the laser-drilled holes H, but these are formed after the resin is laid down; this is explained on page 14. New claims 24-27 are supported in the last five lines of the middle full paragraph on page 13, and in the drawing.